

03-28-01

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sir:

This is a request for filing a continuation application under 37 CFR 1.53 (b) as a **divisional application** of prior application No. **09/329,648** / filed on **6/9/99**.

Prior application information: Examiner: **CHAMBLISS, ALONZO** Group Art Unit: **2814**

The entire disclosure of the prior application, from which an oath or declaration is supplied herewith as indicated below, is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated by reference.

Transmitted herewith for filing is the patent application of

Inventor(s): MING-DOU KER

HSIN-CHIN JIANG

For: LOW-CAPACITANCE BONDING PAD FOR SEMICONDUCTOR DEVICE

Enclosed are:

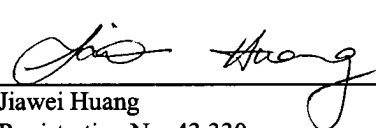
- (X) Specification in (19) pages.
- (X) (12) sheets of drawings.
- (X) Preliminary amendment.
- (X) A copy of Declaration and Power of Attorney from the prior application is enclosed.
- (X) Return prepaid postcard.

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$ 710	\$ 710
Total Claims	16 - 20 = 0	×	\$ 18	\$ 0
Independent Claims	5 - 3 = 2	×	\$ 80	\$ 160
If application contains any multiple dependent claims(s), then add			\$ 270	\$ 0
For a Large Entity:	TOTAL FILING FEE			\$ 870

- (X) A check in the amount of \$870 to cover the filing fee is enclosed.
- (X) The commissioner is authorized to charge any additional necessary fee to Account No. 50-0710 (Order No. JCLA4280-D2). A duplicate copy of this sheet is enclosed.

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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No. : JCLA4280-D2
Inventor(s) : MING-DOU KER
HSIN-CHIN JIANG
For : LOW-CAPACITANCE BONDING PAD FOR SEMICONDUCTOR
DEVICE
"Express Mail"
Mailing Label No. : EL722767473US
Date of Deposit : March 27, 2001

I hereby certify that the accompanying

Transmittal in Duplicate; Specification in 19 page(s); 12 sheet of drawing(s);
Copies of Declaration and Power of Attorney from prior application; Preliminary
Amendment; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee"
service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant
Commissioner for Patents, Washington, D.C. 20231.



Michelle Chang

03/27/01 11059 U.S. PTO

PATENT APPLICATION SERIAL NO. _____

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE
FEE RECORD SHEET

03/29/2001 TGEDAMU1 00000032 09818449

01 FC:101	710.00 OP
02 FC:102	160.00 OP